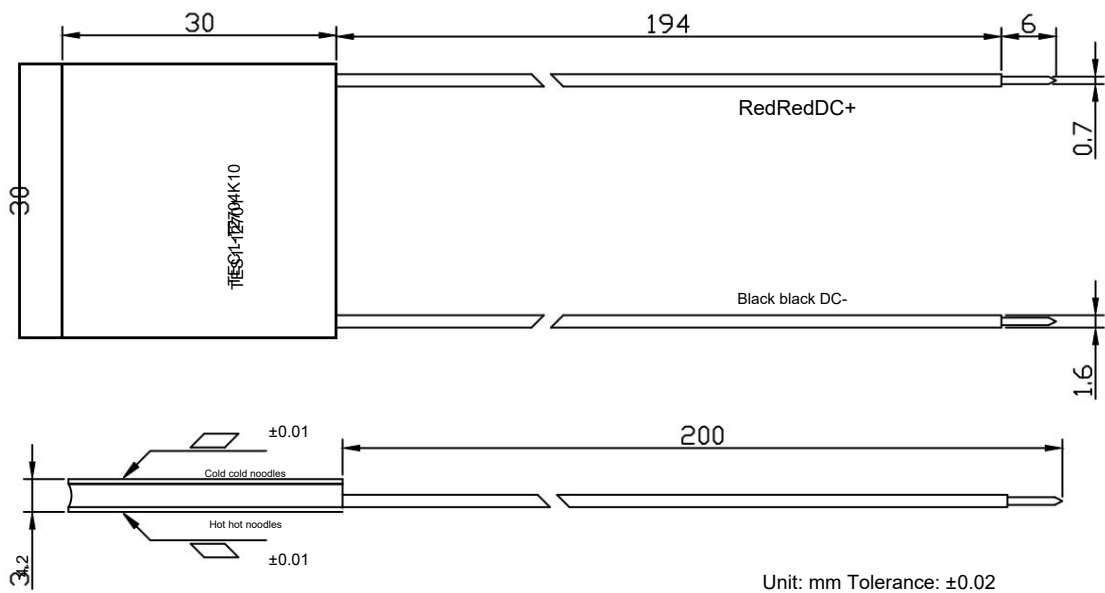


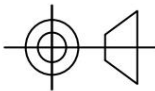
Semiconductor refrigeration chip specifications

TES1-12701

1. Dimensions



2. Performance indicators

Product	Model	TES1-12701	Dimensions	Size	30x30x4.2mm	
Maximum voltage	Vmax	DC15.2V	Internal resistance	Impe	8.47Ω	
Maximum current	Imax	1.4A	Solder type	Solder	Bi67+Sn33	
Maximum temperature difference	DTmax	60℃	Packaging material	materia	96% alumina+CU2	
Input power	Wmax	16.8W	Sealing material	Seal up	704 silicone rubber	
Cooling capacity	Cool	13.1W	Lead specifications Wire standard	Wire gauge	length	terminal
Maximum temperature resistance	Kmax	≤150℃		UL1007	+Red 200	NO
				22AGW	-Black 200	
			Making orders	Name	Huang Dong	
			Update date	Date	2023-01-09	
Thermoelectric Cooler						